

Synthetic Resin Bond Applications (Please call ASA for questions regarding application use for bonds)

- B7 Bond Soft Dry grinding Bond used for:
- a. Thin Kerf cut off wheels
 - b. Mono Set Tool and Cutter Grinders
- B Standard ASA Bond, harder than B7. Application use:
- a. Wet or Dry grinding
 - b. Combination Steel Carbide grinding
 - c. Dry grinding on Mono Set or Cincinnati Tool and Cutter Grinders
- B10 Universal bond, soft grinding but wear resistant used for:
- a. Surface grinding
 - b. ID Grinding
 - c. OD Grinding
 - d. Center less Grinding
- B60 Cool grinding, harder than B10 bond, Wet/dry Grinding but wear resistant used for:
- a. Cut-Off Wheels
 - b. Slot Grinding Collets
 - c. Profile Grinding
 - d. Fluting
- BC5 ASA Standard for cutting tool manufacture re-sharpening. Copper fill resin bond used for:
- a. Standard fluting wide profiles
- BC3 Copper resin bond. Softer than B80 bonds. Used for:
- a. Standard Bond for deep profiles
 - b. Flute grinding with narrow profiles
 - c. Stainless and quartz applications
- BNN (BSA) Profiling Bond. Used for:
- a. Diamond and CBN wheels Corner Holding Bond
 - b. Punch grinding
 - c. Gashing
 - d. Some fluting and polishing operations
- BNGT Low wear bonds
CNC applications
- BAD Used for micron sizes
- BF Bak-a-Lite free cutting bond. Used for
- a. Grinding Diamond and Ceramic Materials